



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC017N04NM5	Issued	24. February 2022
MA#	MA005400467		
Package	PG-TDSON-8-36	Weight*	115.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.110	0.96	0.96	9647	9647
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		450	
	non noble metal	copper	7440-50-8	51.740	44.96	45.01	449576	450161
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	375	375
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		710	
	plastics	epoxy resin	-	6.453	5.61		56067	
	inorganic material	silicondioxide	60676-86-0	34.305	29.81	35.49	298075	354852
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12091	12091
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1684	1684
solder	non noble metal	tin	7440-31-5	0.030	0.03		259	
	noble metal	silver	7440-22-4	0.037	0.03		323	
	non noble metal	lead	7439-92-1	1.422	1.24	1.30	12355	12937
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	17.131	14.89	14.90	148856	149050
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9203	9203
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com